External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die		Lead Dioxide (PbO2)	1309-60-0	0.00435	0.66	0.066
	Doped silicon	Silicon (Si)	7440-21-3	0.65408	99.34	9.934
			Subtotal	0.65843	100	10
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.04674	10.0	0.70985
	Silver alloy	Silver (Ag)	7440-22-4	0.00935	2.0	0.14197
	Lead alloy	Lead (Pb)	7439-92-1	0.4113	88.0	6.24666
			Subtotal	0.46739	100	7.09848
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.56548	100.0	8.58835
			Subtotal	0.56548	100	8.58835
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.00967	0.03	0.14694
	Pure metal layer	Zinc (Zn)	7440-66-6	0.00645	0.02	0.09796
	Pure metal layer	Tin (Sn)	7440-31-5	0.00967	0.03	0.14694
	Pure metal layer	Iron (Fe)	7439-89-6	0.03547	0.11	0.53877
	Pure metal layer	Copper (Cu)	7440-50-8	32.18792	99.81	488.8594
			Subtotal	32.24918	100	489.79001
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.31934	100.0	4.85
			Subtotal	0.31934	100	4.85
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	5.25921	8.0	79.8752
	Filler	Silica fused	60676-86-0	53.24954	81.0	808.7364
	Metal hydroxide	Metal hydroxide		0.46018	0.7	6.98908
	Carbon Black	Carbon black	1333-86-4	0.19722	0.3	2.99532
	Polymer	Epoxy resin system		6.57402	10.0	99.844
			Subtotal	65.74017	100	998.44
			Total	99.99999	100	1518.76684

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